

PHONE: 303 554-8371 FAX: 303 554-8667

Facsimile

Date: May 19, 2003
Deliver To: John Vigushin (GAU 2827)
Fax: 703-746-4343
Re: Serial No. 10/002,732 (docket no. P012-1)
From: David M. Sigmond

The following documents are attached:

1. Second Preliminary Amendment (5 pages)
2. Markstein et al. (6 pages) (Ref AP, PTO-1449, p1)
3. Elenius (3 pages) (Ref AQ, PTO-1449, p1)
4. Erickson (3 pages) (Ref AP, PTO-1449, p2)
5. Kuchenmeister et al. (5 pages) (Ref AQ, PTO-1449, p2)
6. Ghaffarian (4 pages) (Ref AP, PTO-1449, p3)

Please note the references are complete (and identical to the original submissions).
The skipped pages are advertisements.

Please let me know if I can assist further.

TOTAL NUMBER OF PAGES: 27 (Including This Page)
If you have any trouble receiving this transmission, please call
David M. Sigmond at (303) 554-8371

SPECIAL INSTRUCTIONS:

The documents accompanying this facsimile transmittal coversheet contain information from David M. Sigmond which may be confidential and/or legally privileged and are valuable, and proprietary to, trade secrets of, and copyrighted by David M. Sigmond or his clients. The documents are intended only for the personal and confidential use of the addressee identified above. If you are not the intended recipient or an agent responsible for delivering these documents to the intended recipient, you are hereby notified that any review, disclosure, copying, distribution or the taking of any action in reliance on the contents of this transmitted information is strictly prohibited.

IF YOU HAVE RECEIVED THIS FACSIMILE IN ERROR, PLEASE IMMEDIATELY NOTIFY DAVID M. SIGMOND SO THAT I CAN ARRANGE FOR THE RETURN OF THE ORIGINAL DOCUMENTS TO ME OR TO THE INTENDED RECIPIENT. THANK YOU.

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Charles W.C. Lin
Title: SUPPORT CIRCUIT WITH A TAPERED THROUGH-HOLE
FOR A SEMICONDUCTOR CHIP ASSEMBLY
Serial No.: 10/002,732 Filed: November 15, 2001
Examiner: Vigushin, J. Group Art Unit: 2827
Atty. Docket No.: P012-1

COMMISSIONER FOR PATENTS
P.O. Box 1450
Alexandria, VA 22313-1450

SECOND PRELIMINARY AMENDMENT

Dear Sir:

Please amend the application as follows.

In the Abstract

Replace the paragraph at page 35, lines 1-19 with the following paragraph:

A support circuit is adapted to be mechanically and electrically coupled to a semiconductor chip such that the support circuit and the chip in combination form a semiconductor chip assembly. The support circuit includes an insulative base and a conductive trace embedded in the insulative base. The conductive trace is a single continuous piece of metal, the conductive trace includes a pillar that extends above the insulative base and a routing line that is substantially covered by and extends below the insulative base, and an opening in the routing line has tapered sidewalls and a diameter that increases as height increases.